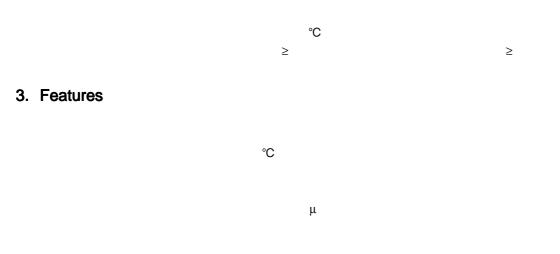


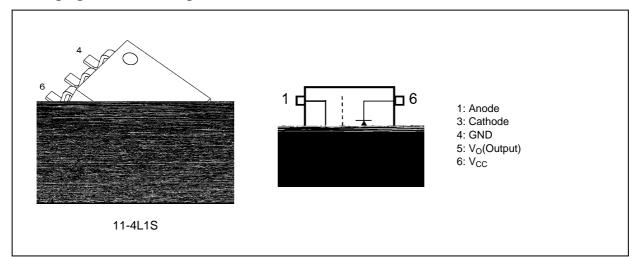
Photocouplers GaA As Infrared LED & Photo IC

TLP2309

- 1. Applications
- 2. General



4. Packaging and Pin Configuration





5. Internal Circuit

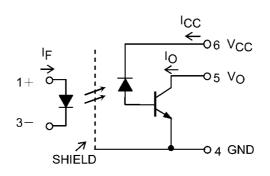


Fig. 5.1 Internal Circuit

6. Principle of Operation

6.1. Truth Table

Input	LED	Output
н	ON	L
L	OFF	Н

6.2. Mechanical Parameters

Characteristics	Min	Unit
Creepage distances	5.0	mm
Clearance distances	5.0	
Internal isolation thickness	0.4	



7. Absolute Maximum Ratings (Note) (Unless otherwise specified, $T_a = 25^{\circ}C$)

	Characteristics		Symbol	
LED	Input forward current		I _F	
	Input forward current derating	(T _a ≥ 100°C)	$\Delta I_F / \Delta T_a$	
	Input forward current (pulsed)		I _{FP}	
	Input forward current derating (pulsed)	$(T_a \ge 100^{\circ}C)$	$\Delta I_{\sf FP}$	
	Peak transient input forward current			
	Peak transient input forward current derating	$(T_a \ge 85^{\circ}C)$		
	Input power dissipation			
	Input power dissipation derating	(T _a ≥ 100°C)		
	Input reverse voltage			
Detector	Output current			
	Peak output current			
	Supply voltage			
	Output voltage			
	Output power dissipation			
	Output power dissipation derating	$(T_a \ge 100^{\circ}C)$		
Common	Operating temperature			
	Storage temperature			
	Lead soldering temperature	(10 s)		
	Isolation voltage	AC, 1 min, R.H. \leq 60%		



9. Electrical Characteristics (Note) (Unless otherwise specified, $T_a = 25^{\circ}C$)

Characteristics	Symbol			Тур.	Max	Unit
Input forward voltage	V _F	I _F = 10 mA	1.45	1.55	1.7	V
Input forward voltage temperature coefficient	$\Delta V_F / \Delta T_a$	$I_F = 10 \text{ mA}, T_a = -40^{\circ}\text{C} \text{ to } 110^{\circ}\text{C}$	—	-2.0	—	mV/°C
Input reverse current	I _R	$V_R = 5 V$	—	_	10	μA
Input capacitance	Ct	V = 0 V, f = 1 MHz	_	60	_	pF
High-level output current	I _{ОН}	$I_F = 0 \text{ mA}, V_O = 5.5 \text{ V}, V_{CC} = 5.5 \text{ V}$	_	3	500	nA
		I _F = 0 mA, V _O = 20 V, V _{CC} = 30 V	_	_	5	μA
		$I_F = 0 \text{ mA}, V_O = 20 \text{ V}, V_{CC} = 30 \text{ V},$ $T_a = 110^{\circ}\text{C}$	_	_	50	
High-level supply current	I _{CCH}	I _F = 0 mA, V _{CC} = 30 V	_	0.01	1	
Current transfer ratio	I _O /I _F	$I_F = 10 \text{ mA}, \text{ V}_O = 0.4 \text{ V}, \text{ V}_{CC} = 3.3 \text{ V}$	15	_	_	%
		$I_F = 16 \text{ mA}, V_O = 0.4 \text{ V}, V_{CC} = 4.5 \text{ V}$	15	_	_	
Low-level output voltage	V _{OL}	$I_F = 16 \text{ mA}, V_{CC} = 4.5 \text{ V}, I_O = 2.4 \text{ mA}$	—	_	0.4	V

Note: All typical values are at $T_a = 25^{\circ}C$.

10. Isolation Characteristics (Unless otherwise specified, $T_a = 25^{\circ}C$)

Characteristics	Symbol	Note	Test Conditions	Min	Тур.	Max	Unit
Total capacitance (input to output)	CS	(Note 1)	V _S = 0 V, f = 1 MHz	_	0.8	_	pF
Isolation resistance	R _S	(Note 1)	V _S = 500 V, R.H. ≤ 60%	1×10 ¹²	1014	_	Ω
Isolation voltage	BVS		AC, 1 min	3750	_	_	Vrms
			AC, 1 s in oil	_	10000	_	
			DC, 1 min in oil	_	10000	_	Vdc

12. Test Circuits and Characteristics Curves

12.1. Test Circuits

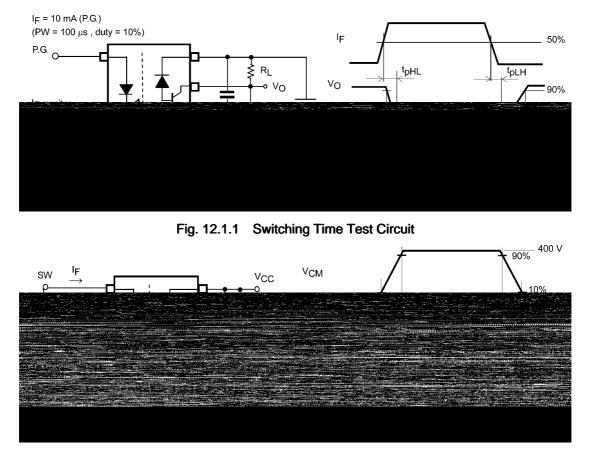


Fig. 12.1.2 Common-Mode Transient Immunity



12.2. Characteristics Curves (Note)

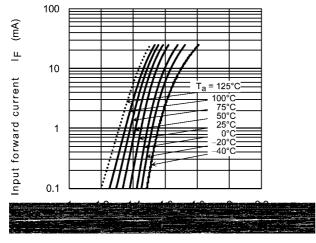
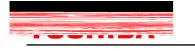


Fig. 12.2.1 I



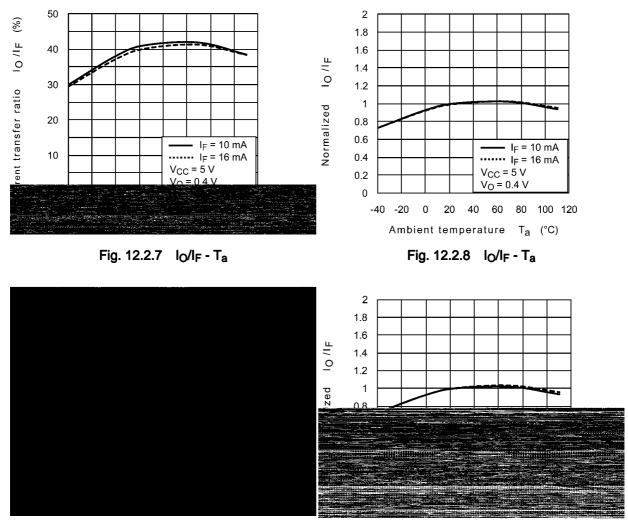
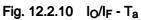
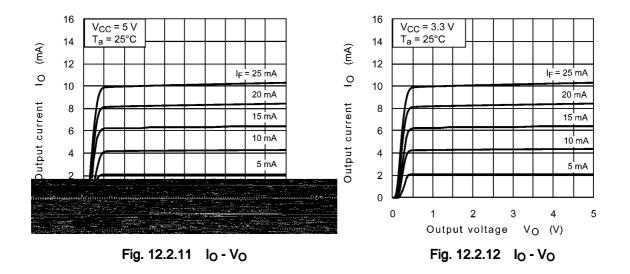
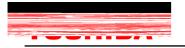


Fig. 12.2.9 I_O/I_F - T_a









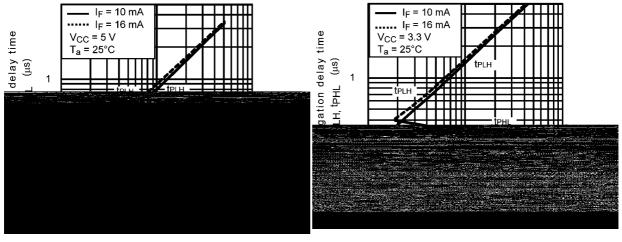


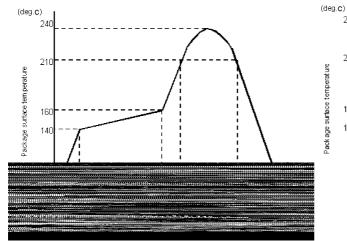
Fig. 12.2.19 t_{PLH}, t_{PHL} - R_L

Fig. 12.2.20 tpLH, tpHL - RL

Note: The above characteristics curves are presented for reference only and not guaranteed by production test.

13. Soldering and Storage

13.1. Precautions for Soldering



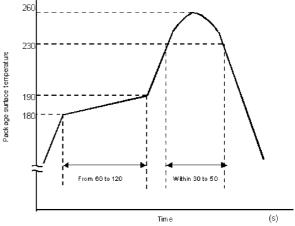
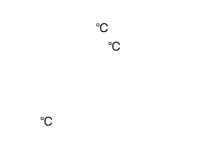
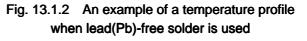


Fig. 13.1.1 An example of a temperature profile when Sn-Pb eutectic solder is used



13.2. Precautions for General Storage



°C

°C °C



14. Land Pattern Dimensions for Reference Only

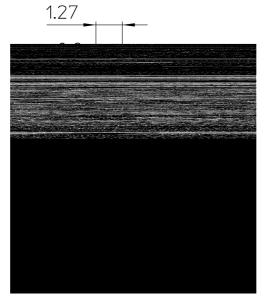


Fig. 14.1 Land Pattern Dimensions for Reference Only (unit: mm)

15. Marking

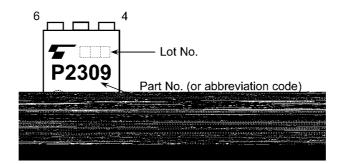
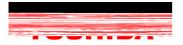


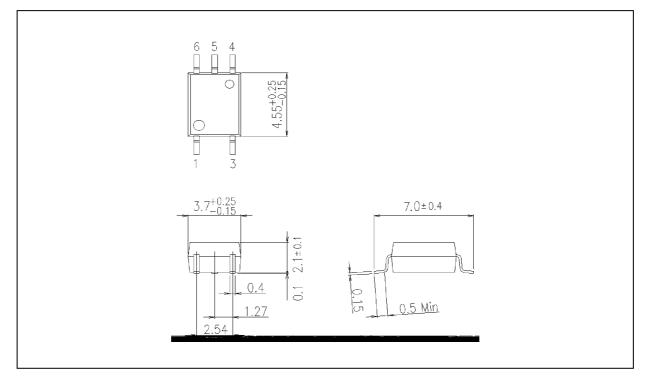
Fig. 15.1 Marking



TLP2309

Package Dimensions

Unit: mm



Weight: 0.08 g (typ.)

Package Name(s) TOSHIBA: 11-4L1S

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